

IN THE SPECIFICATION:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 10/205,943, filed July 25, 2002, ~~pending~~ now U.S. Patent 6,604,671, issued August 8, 2003, which is a continuation of application Serial No. 09/941,019, filed August 28, 2001, now U.S. Patent 6,435,400, issued August 20, 2002, which is a continuation of application Serial No. 09/407,483, filed September 28, 1999, now U.S. Patent 6,325,275, issued December 4, 2001, which is a continuation of application Serial No. 08/865,911, filed May 30, 1997, now U.S. Patent 6,000,599, issued December 14, 1999, which is a continuation of application Serial No. 08/597,616, filed February 6, 1996, now U.S. Patent 5,647,528, issued July 15, 1997.

Please replace paragraph number [0029] with the following rewritten paragraph:

[0029] Referring to drawing Fig. 5, an independent clamp-22— 22 is shown having a modified end or foot 23' located on the end thereof. The end or foot 23' may be integrally attached to the clamp-22— 22 or may have an articulated mounting arrangement, such as shown in drawing Fig. 4. In this instance, the modified end or foot 23' is generally semicircular, or arcuate, in configuration so as to engage a large portion of the end 15 of the lead finger 14 surrounding the bonding apparatus 26 during the wire bonding operation to hold the end 15 in position.

Please replace paragraph number [0030] with the following rewritten paragraph:

[0030] Referring to drawing Fig. 6, the independent clamp 24 is shown in relation to the bonding apparatus 26 on the end 15 of a lead finger 14 as well as further being shown in relation to a second independently actuated clamp 150 located thereon during wire bonding operations. The second independently actuated clamp 150 may be of any suitable type and structure such as described and illustrated hereinbefore. The clamp 24 and second-clamp

clamp 150 may be actuated independently of each other and independently of the bonding apparatus 26 as described and illustrated hereinbefore.